ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATIONAL OF THE STREET	C. Bannockb	ourn. Illinois. A	All rights reserved untions.	nder both lev	nis docume vel parts, th	ent is a declaration ne declaration en	n of the substan compasses all lo	ces within the manufactu ower level materials for w	rer listed i hich the n	tem. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Dist				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information				on				
Supplier Information													
Company name*	Company unique ID			τ	Unique ID Authority				Response Date*				
onsemi									2024-05-11				
Contact Name Title - Contact			ct			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
Product-Env-Stewards	Product Enviro Compliance			:	NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	er Mfr Item Name			Effective Date	Version	Manufacturing Site	,	Weight*	UOM	Unit Type	
	NCID92	ICID9200R2 High Speed Dual C T&R		Channel Digital Is	olator	2024-05-11		PBB		423.399	mg	Each	
Manufacturing Proccess Informat	ion												
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base Alloy		J-STD-020 MSL R	ating	Peak Proces	s Body Temper	ature Max Time at Peak	Temperat	ure Numb	er of Reflow Cyc	cles		
Matte Tin (Sn) - annealed CU Alloy		1		260	С	30	secon	ds 3					
Comments													
evel 1 - maximum time at peak temperatu	re during sol	dering is 10-3	0 seconds										
For more information regarding material of	composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	54.376	mg	Supplier	Silver (Ag)	7440-22-4		0.0816	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		38.7918	mg
			В	Nickel (Ni)	7440-02-0		0.1305	mg
			Supplier	Copper (Cu)	7440-50-8		15.3721	mg
Die	2.997	mg	Supplier	Silicon (Si)	7440-21-3		2.997	mg
Epoxy	0.036	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0029	mg
			Supplier	Proprietary	Proprietary Data		0.0032	mg
			Supplier	Bismaleimide	13676-54-5		0.0097	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0004	mg
			Supplier	PTFE	9002-84-0		0.0198	mg
Lead Frame	65.486	mg	Supplier	Silver (Ag)	7440-22-4		0.1965	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1244	mg
			Supplier	Iron (Fe)	7439-89-6		1.6961	mg
			Supplier	Copper (Cu)	7440-50-8		63.3773	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0917	mg
Mold Compound-Black	296.395	mg		Epoxy resin	proprietary data		17.7837	mg
			Supplier	Phenolic Resin	Proprietary Data		17.7837	mg
			Supplier	Carbon Black (C)	1333-86-4		1.482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		251.9357	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.4099	mg
lating	3.143	mg	Supplier	Tin (Sn)	7440-31-5		3.143	mg
Solder Paste	0.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0149	mg
			Α	Lead (Pb)	7439-92-1	7a	0.5504	mg
			Supplier	Tin (Sn)	7440-31-5		0.0298	mg
Wire Bond - Au	0.371	mg	Supplier	Gold (Au)	7440-57-5		0.371	mg